

**High-temp.-resistant hot-melt adhesive**

Publication number: CN1401724  
Publication date: 2003-08-12  
Inventor: ZHANG WANXI (CN); ZHANG CHANGCHUN (CN); LI  
XIAOMING (CN)  
Applicant: LIMV JILIN (CN)  
Classification:  
International: C09J177/00; C09J177/00; IPC1-7: C09J177/00  
European:  
Application number: CN20021033016 20020924  
Priority number(s): CN20021033016 20020924

Report a data error here

**Abstract of CN1401724**

A high-temp.-resistant hot-melt adhesive for electronic device is prepared from polyamide (55-70 wt.%), EVA (0-5 wt.%), rosin (7.5-10 wt.%), glyceride (7.5-10 wt.%), nano-Al<sub>2</sub>O<sub>3</sub> (12-15 wt.%), nano zinc oxide (3-5 wt.%) and nano magnesium oxide (0-3 wt.%). Its advantages are high working temp (130-150 deg.C) and no odour release.

Data supplied from the esp@cenet database - Worldwide